

N-Channel 100-V (D-S) MOSFET

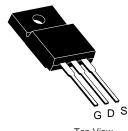
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
100	0.0085 at V _{GS} = 10 V	90		
	0.0100 at V _{GS} = 6 V	85		

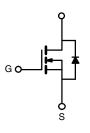
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

ABSOLUTE MAXIMUM RATI	NGS T _A = 25 °C, unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C	I _D	90		
Continuous Diain Curient (1) = 130 C)	T _C = 125 °C		70 ^a	^	
Pulsed Drain Current		I _{DM}	287	Α	
Avalanche Current	L = 0.1 mH	I _{AS}	75		
Single Pulse Avalanche Energy ^b	L = 0.1 IIII I	E _{AS}	280	mJ	
Mariana Bana Biraira tirab	$T_C = 25 ^{\circ}C (TO-220F)$	P _D	56	W	
Maximum Power Dissipation ^b	T _A = 25 °C (TO-220F)		3.75		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount (TO-220) d	- R _{thJA}	40	
Junction-to-Ambient	Free Air (TO-220)		62.5	°C/W
Junction-to-Case		R _{thJC}	0.6	

Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			v	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.0095			
		V _{GS} = 6 V, I _D = 20 A		0.0100		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.0160			
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.0210			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b	•						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		6550		pF	
Output Capacitance	C _{oss}			665			
Reverse Transfer Capacitance	C _{rss}			265			
Total Gate Charge ^c	Q_g			105			
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 85 \text{ A}$		17		nC	
Gate-Drain Charge ^c	Q_{gd}	1		23		1	
Turn-On Delay Time ^c	t _{d(on)}			12	25		
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135	ns	
Turn-Off DelayTime ^c	t _{d(off)}	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85		
Fall Time ^c	t _f	1		130	195		
Source-Drain Diode Ratings and Char	acteristics T _C	= 25 °C ^b		•			
Continuous Current	Is			90			
Pulsed Current	I _{SM}			240		Α	
Forward Voltage ^a	V _{SD}	I _F = 85 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			85	140	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q _{rr}	_		0.17	0.35	μС	

Notes:

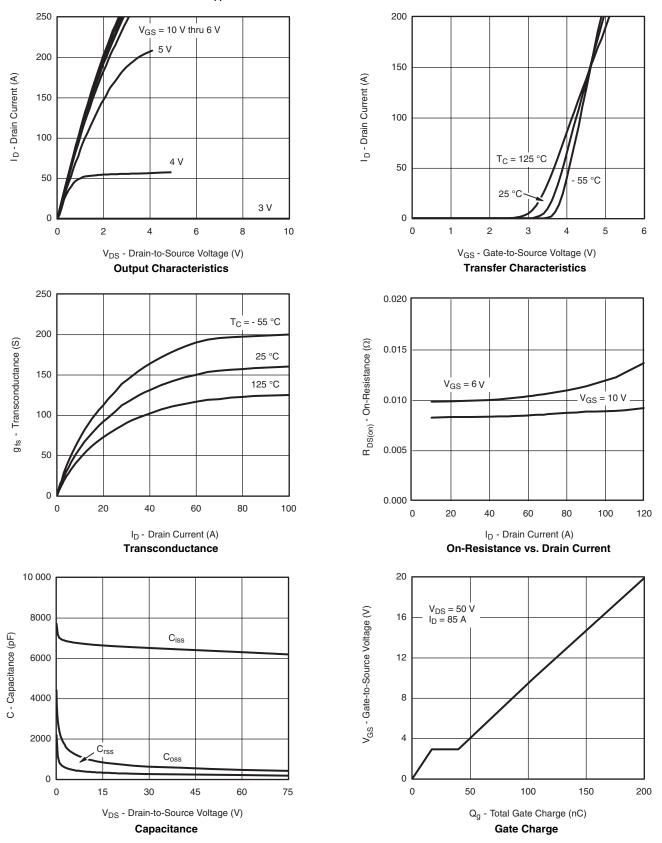
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- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



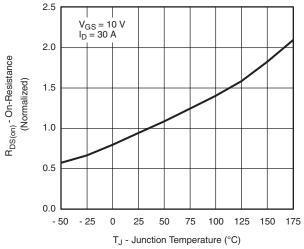
TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



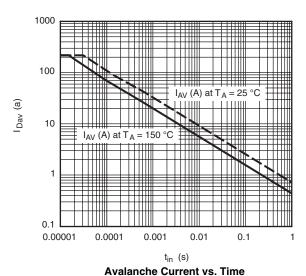
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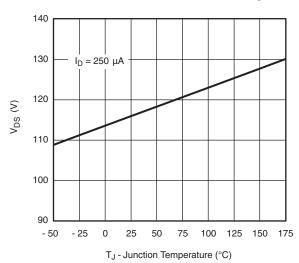
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On-Resistance vs. Junction Temperature



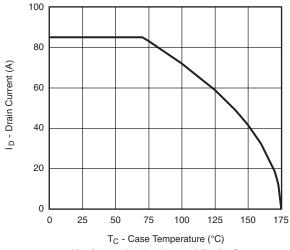
Source-Drain Diode Forward Voltage

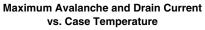


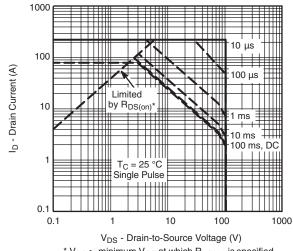
T_J - Drain-Source Breakdown vs. Junction-Temperature



THERMAL RATINGS

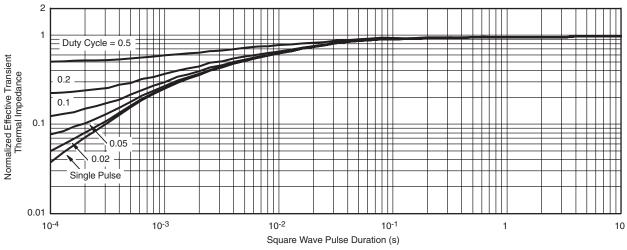






* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



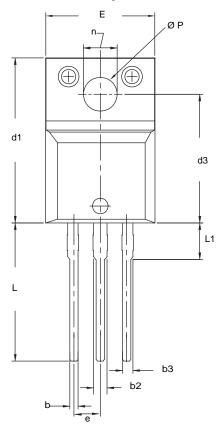
Normalized Thermal Transient Impedance, Junction-to-Case

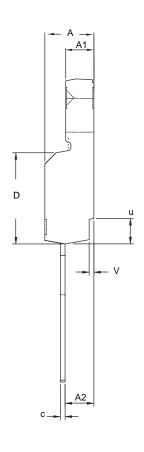
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TO-220 FULLPAK (HIGH VOLTAGE)





	MILLI	METERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
С	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
е	2.54	2.54 BSC		BSC
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
ØΡ	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020
N: X09-0126-Rev. B, 2 /G: 5972	26-Oct-09			

Notes

- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.



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